

Title (en)

Grounding devices.

Title (de)

Erdungsvorrichtungen.

Title (fr)

Dispositifs de mise à la terre.

Publication

EP 0136039 A2 19850403 (EN)

Application

EP 84305590 A 19840817

Priority

US 52495883 A 19830819

Abstract (en)

Grounding devices comprise a metallic central member and a conductive polymer member which surrounds that part of the metallic member which is buried within the ground. The conductive polymer member retards corrosion of the central member by moist soils, and thus increases the life of the device and/or makes it possible to use steel or other relatively cheap metals in place of copper. Preferably the conductive polymer increases in resistivity when its temperature is raised by passage of a grounding current therethrough, so that current density tends to be equalized over the surface of the device.

IPC 1-7

H01R 4/66

IPC 8 full level

H01R 4/66 (2006.01)

CPC (source: EP)

H01R 4/66 (2013.01)

Cited by

CN105514629A; CN109616786A; CN102420358A; EP0415950A4; CN106785509A; CN110854557A; CN106356651A; CN112688091A; FR2871953A1; CN105655738A; CN112079637A; EP3428932A1; CN117673780A; US10181362B2

Designated contracting state (EPC)

AT BE CH DE FR GB IT LI NL SE

DOCDB simple family (publication)

EP 0136039 A2 19850403; JP S6062070 A 19850410

DOCDB simple family (application)

EP 84305590 A 19840817; JP 17233084 A 19840817